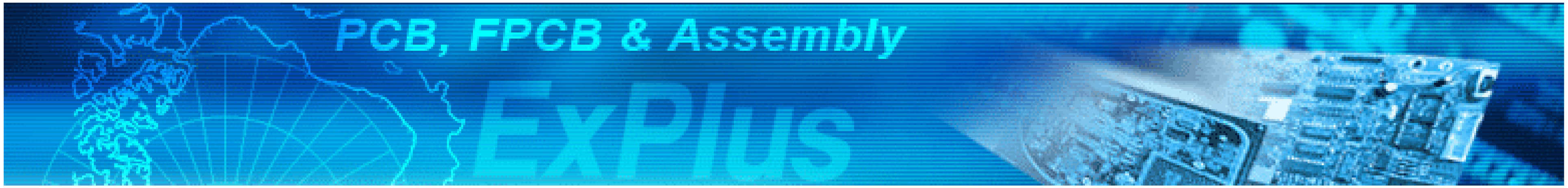

PCB Production Capability

ExPlus Group

- **Min Solder Mask Thickness:** 0.4 mils (0.01 mm)
- HDI PROCESS, BLIND/BURIED VIAS
- **MIN. INNER LAYER:** 3 mil (0.076 mm)
- **ASPECT RATIO:** 10 : 1
- **CONTROLLED IMPEDANCE:** +/- 10%
- **Board FLATNESS TOLERANCE:** 0.7%
- **DEVIATION:**
  A. LAYER TO LAYER +/- 3 mil (0.075 mm)
  B. HOLE SIZE (NPTH)+/-2 mil (0.05 mm)
  (PTH) +-3 mil (0.075 mm)
  C. HOLE LOCATION +/-3 mil (0.075 mm
- **Lead Time:** Sample: 1~3 Work Days
  Standard: 2~3 Weeks

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UL E210681
SGS RoHS